STMicroelectronics - ST72F324BJ4T6TR Datasheet





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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Not For New Designs
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	32
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f324bj4t6tr

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2 Pin description













		Pin		Le	vel			Por	rt					
N	о.		be		t		Input C		Inpu		Output		Main function	Alternate function
LQFP44	LQFP32	Name	Ty Input		Outpu	float	ndw	int	ana	ОD	дд	(after reset)	Alternate function	
2	28	РВ0	I/O	CT		x		ei2		x	x	Port B0	Caution: Negative current injection not allowed on this pin on 8/16 Kbyte Flash devices. ⁽⁴⁾	
3	-	PB1	I/O	C _T		х		ei2		Х	Х	Port B1		
4	-	PB2	I/O	CT		X		ei2		Х	Х	Port B2		
5	29	PB3	I/O	CT		Х		ei2		х	Х	Port B3		

Table 2. Device pin description (continued)

1. It is mandatory to connect all available V_{DD} and V_{REF} pins to the supply voltage and all V_{SS} and V_{SSA} pins to ground.

2. On the chip, each I/O port has eight pads. Pads that are not bonded to external pins are in input pull-up configuration after reset. The configuration of these pads must be kept at reset state to avoid added current consumption..

3. OSC1 and OSC2 pins connect a crystal/ceramic resonator, or an external source to the on-chip oscillator; see *Section 1: Description* and *Section 12.6: Clock and timing characteristics* or more details.

4. For details refer to *Section 12.9.1 on page 162*

Legend / Abbreviations for Table 2:

Type:I = input, O = output, S = supply Input level: A = Dedicated analog input In/Output level: C = CMOS $0.3V_{DD}/0.7_{DD}$ $C_T = CMOS 0.3V_{DD}/0.7_{DD}$ with input trigger Output level: HS = 20mA high sink (on N-buffer only) Port and control configuration:

Input:float = floating, wpu = weak pull-up, int = interrupt^(a), ana = analog ports Output:OD = open drain^(b), PP = push-pull



a. In the interrupt input column, "eiX" defines the associated external interrupt vector. If the weak pull-up column (wpu) is merged with the interrupt column (int), then the I/O configuration is pull-up interrupt input, else the configuration is floating interrupt input.

b. In the open drain output column, 'T' defines a true open drain I/O (P-Buffer and protection diode to V_{DD} are not implemented). See Section 9: I/O ports and Section 12.9: I/O port pin characteristics for more details.

Address	Block	Register label	Register name	Reset status ⁽¹⁾	Remarks ⁽¹⁾			
000Fh 0010h 0011h	Port F ⁽¹⁾	PFDR PFDDR PFOR	Port F data register Port F data direction register Port F option register	00h ⁽²⁾ 00h 00h	R/W R/W R/W			
0012h to 0020h	Reserved area (15 bytes)							
0021h 0022h 0023h	SPI	SPIDR SPICR SPICSR	SPI data I/O register SPI control register SPI control/status register	xxh 0xh 00h	R/W R/W R/W			
0024h 0025h 0026h 0027h	ISPR0 ISPR1 ITC ISPR2 ISPR3		Interrupt software priority register 0 Interrupt software priority register 1 Interrupt software priority register 2 Interrupt software priority register 3	FFh FFh FFh FFh	R/W R/W R/W R/W			
0028h		EICR	External interrupt control register	00h	R/W			
0029h	Flash	FCSR	Flash control/status register	00h	R/W			
002Ah	Watchdog	WDGCR	Watchdog control register	7Fh	R/W			
002Bh	SI	SICSR	System integrity control/status register	000x 000xb	R/W			
002Ch 002Dh	MCC	MCCSR MCCBCR	Main clock control/status register Main clock controller: beep control register	00h 00h	R/W R/W			
002Eh to 0030h			Reserved area (3 bytes)					
0031h 0032h 0033h 0034h 0035h 0036h 0037h 0038h 0039h 003Ah 003Bh 003Ch 003Ch 003Eh 003Fh	Timer A	TACR2 TACR1 TACSR TAIC1HR TAIC1LR TAOC1HR TAOC1LR TAOC1LR TACHR TACLR TAACHR TAACLR TAACLR TAIC2HR TAIC2LR TAOC2HR TAOC2LR	Timer A control register 2 Timer A control register 1 Timer A control/status register Timer A input capture 1 high register Timer A input capture 1 low register Timer A output compare 1 high register Timer A output compare 1 low register Timer A counter high register Timer A counter low register Timer A alternate counter high register Timer A alternate counter low register Timer A alternate counter low register Timer A input capture 2 high register Timer A output compare 2 high register Timer A output compare 2 low register	00h 00h xxxx x0xxb xxh 80h 00h FFh FCh FCh FCh xxh xxh 80h 00h	R/W R/W Read only Read only R/W R/W Read only Read only Read only Read only Read only Read only Read only Read only R/W			
0040h			Reserved area (1 byte)					

Table 3. Hardware register map (continued)





7 Interrupts

7.1 Introduction

The ST7 enhanced interrupt management provides the following features:

- Hardware interrupts
- Software interrupt (TRAP)
- Nested or concurrent interrupt management with flexible interrupt priority and level management:
 - up to 4 software programmable nesting levels
 - up to 16 interrupt vectors fixed by hardware
 - 2 non-maskable events: reset, TRAP

This interrupt management is based on:

- Bit 5 and bit 3 of the CPU CC register (I1:0)
- Interrupt software priority registers (ISPRx)
- Fixed interrupt vector addresses located at the high addresses of the memory map (FFE0h to FFFFh) sorted by hardware priority order

This enhanced interrupt controller guarantees full upward compatibility with the standard (not nested) ST7 interrupt controller.

7.2 Masking and processing flow

The interrupt masking is managed by the I1 and I0 bits of the CC register and the ISPRx registers which give the interrupt software priority level of each interrupt vector (see *Table 14*). The processing flow is shown in *Figure 16*.

When an interrupt request has to be serviced:

- Normal processing is suspended at the end of the current instruction execution.
- The PC, X, A and CC registers are saved onto the stack.
- I1 and I0 bits of CC register are set according to the corresponding values in the ISPRx registers of the serviced interrupt vector.
- The PC is then loaded with the interrupt vector of the interrupt to service and the first instruction of the interrupt service routine is fetched (refer to *Table 25: Interrupt mapping* for vector addresses).

The interrupt service routine should end with the IRET instruction which causes the contents of the saved registers to be recovered from the stack.

Note: As a consequence of the IRET instruction, the I1 and I0 bits will be restored from the stack and the program in the previous level will resume.





Figure 22. Slow mode clock transitions

8.3 Wait mode

Wait mode places the MCU in a low power consumption mode by stopping the CPU.

This power saving mode is selected by calling the 'WFI' instruction.

All peripherals remain active. During Wait mode, the I[1:0] bits of the CC register are forced to '10', to enable all interrupts. All other registers and memory remain unchanged. The MCU remains in Wait mode until an interrupt or reset occurs, whereupon the Program Counter branches to the starting address of the interrupt or reset service routine. The MCU will remain in Wait mode until a reset or an interrupt occurs, causing it to wake up. Refer to *Figure 23*.





 Before servicing an interrupt, the CC register is pushed on the stack. The I[1:0] bits of the CC register are set to the current software priority level of the interrupt routine and recovered when the CC register is popped.











- 1. WDGHALT is an option bit. See *Section 14.1 on page 179* for more details.
- 2. Peripheral clocked with an external clock source can still be active.
- 3. Only some specific interrupts can exit the MCU from Halt mode (such as external interrupt). Refer to *Table 25: Interrupt mapping* for more details.
- Before servicing an interrupt, the CC register is pushed on the stack. The I[1:0] bits of the CC register are set to the current software priority level of the interrupt routine and recovered when the CC register is popped.





Figure 28. I/O port general block diagram

Table 28.I/O port mode options

	Configuration mode	Pull-up	D -buffor	Diodes		
	Comguration mode	Full-up	r-bullet	to V _{DD} ⁽¹⁾	to $V_{SS}^{(2)}$	
Input	Floating with/without Interrupt	Off ⁽³⁾	Off		On	
mput	Pull-up with/without Interrupt	On ⁽⁴⁾	Oli	On		
	Push-pull	Off	On	OII		
Output	Open drain (logic level)	Oli	Off			
	True open drain	NI	NI	NI ⁽⁵⁾		

1. The diode to V_{DD} is not implemented in the true open drain pads.

2. A local protection between the pad and V_{SS} is implemented to protect the device against positive stress.

3. Off = implemented not activated.

4. On = implemented and activated.

5. NI = not implemented



10.2.2 Clock-out capability

The clock-out capability is an alternate function of an I/O port pin that outputs the f_{CPU} clock to drive external devices. It is controlled by the MCO bit in the MCCSR register.

Caution: When selected, the clock out pin suspends the clock during Active Halt mode.

10.2.3 Real-time clock (RTC) timer

The counter of the real-time clock timer allows an interrupt to be generated based on an accurate real-time clock. Four different time bases depending directly on f_{OSC2} are available. The whole functionality is controlled by four bits of the MCCSR register: TB[1:0], OIE and OIF.

When the RTC interrupt is enabled (OIE bit set), the ST7 enters Active Halt mode when the HALT instruction is executed. See *Section 8.4: Active Halt and Halt modes on page 54* for more details.

10.2.4 Beeper

The beep function is controlled by the MCCBCR register. It can output three selectable frequencies on the Beep pin (I/O port alternate function).



Figure 33. Main clock controller (MCC/RTC) block diagram



10.3.4 Low power modes

Table 46.Effect of low power modes on 16-bit timer

Mode	Description
Wait	No effect on 16-bit timer. Timer interrupts cause the device to exit from Wait mode.
Halt	16-bit timer registers are frozen. In Halt mode, the counter stops counting until Halt mode is exited. Counting resumes from the previous count when the MCU is woken up by an interrupt with Exit from Halt mode capability or from the counter reset value when the MCU is woken up by a reset. If an input capture event occurs on the ICAP <i>i</i> pin, the input capture detection circuitry is armed. Consequently, when the MCU is woken up by an interrupt with Exit from Halt mode capability, the ICF <i>i</i> bit is set, and the counter value present when exiting from Halt mode is captured into the IC <i>i</i> R register.

10.3.5 Interrupts

Table 47.	16-bit timer interrupt control/wake-up capability ⁽¹⁾
lable 47.	16-bit timer interrupt control/wake-up capability

Interrupt event	Event flag	Enable Control bit	Exit from WAIT	Exit from HALT	
Input Capture 1 event/counter reset in PWM mode	ICF1	ICIE			
Input Capture 2 event	ICF2				
Output Compare 1 event (not available in PWM mode)	OCF1		Yes	No	
Output Compare 2 event (not available in PWM mode)	OCF2	UCIE			
Timer Overflow event	TOF	TOIE			

1. The 16-bit timer interrupt events are connected to the same interrupt vector (see *Section 7: Interrupts*). These events generate an interrupt if the corresponding Enable Control bit is set and the interrupt mask in the CC register is reset (RIM instruction).



Bit	Name	Function
7	OCIE	Output Compare 1 Pin Enable This bit is used only to output the signal from the timer on the OCMP1 pin (OLV1 in Output Compare mode, both OLV1 and OLV2 in PWM and One-Pulse mode). Whatever the value of the OC1E bit, the Output Compare 1 function of the timer remains active. 0: OCMP1 pin alternate function disabled (I/O pin free for general-purpose I/O). 1: OCMP1 pin alternate function enabled.
6	OC2E	Output Compare 2 Pin Enable This bit is used only to output the signal from the timer on the OCMP2 pin (OLV2 in Output Compare mode). Whatever the value of the OC2E bit, the Output Compare 2 function of the timer remains active. 0: OCMP2 pin alternate function disabled (I/O pin free for general-purpose I/O). 1: OCMP2 pin alternate function enabled.
5	OPM	One Pulse Mode 0: One Pulse mode is not active. 1: One Pulse mode is active, the ICAP1 pin can be used to trigger one pulse on the OCMP1 pin; the active transition is given by the IEDG1 bit. The length of the generated pulse depends on the contents of the OC1R register.
4	PWM	 Pulse Width Modulation 0: PWM mode is not active. 1: PWM mode is active, the OCMP1 pin outputs a programmable cyclic signal; the length of the pulse depends on the value of OC1R register; the period depends on the value of OC2R register.
3:2	CC[1:0]	Clock Control The timer clock mode depends on these bits. 00: Timer clock = $f_{CPU}/4$ 01: Timer clock = $f_{CPU}/2$ 10: Timer clock = $f_{CPU}/8$ 11: Timer clock = external clock (where available) <i>Note: If the external clock pin is not available, programming the external clock configuration stops the counter.</i>
1	IEDG2	 Input Edge 2 This bit determines which type of level transition on the ICAP2 pin will trigger the capture. 0: A falling edge triggers the capture. 1: A rising edge triggers the capture.
0	EXEDG	 External Clock Edge This bit determines which type of level transition on the external clock pin EXTCLK will trigger the counter register. 0: A falling edge triggers the counter register. 1: A rising edge triggers the counter register.

 Table 50.
 CR2 register description



Input Capture 1 Low Register (IC1LR)

This is an 8-bit register that contains the low part of the counter value (transferred by the input capture 1 event).



Output Compare 1 High Register (OC1HR)

This is an 8-bit register that contains the high part of the value to be compared to the CHR register.



Output Compare 1 Low Register (OC1LR)

This is an 8-bit register that contains the low part of the value to be compared to the CLR register.



Output Compare 2 High Register (OC2HR)

This is an 8-bit register that contains the high part of the value to be compared to the CHR register.





Note: In slave mode, continuous transmission is not possible at maximum frequency due to the software overhead for clearing status flags and to initiate the next transmission sequence.

10.4.3 General description

Figure 49 shows the serial peripheral interface (SPI) block diagram. The SPI has three registers:

- SPI Control Register (SPICR)
- SPI Control/Status Register (SPICSR)
- SPI Data Register (SPIDR)

The SPI is connected to external devices through four pins:

- MISO: Master In / Slave Out data
- MOSI: Master Out / Slave In data
- SCK: Serial Clock out by SPI masters and input by SPI slaves
- SS: Slave select: This input signal acts as a 'chip select' to let the SPI master communicate with slaves individually and to avoid contention on the data lines. Slave SS inputs can be driven by standard I/O ports on the master MCU.





Functional description

A basic example of interconnections between a single master and a single slave is illustrated in *Figure 49*.



Bit	Name	Function
7	SPIF	 Serial Peripheral data transfer flag This bit is set by hardware when a transfer has been completed. An interrupt is generated if SPIE = 1 in the SPICR register. It is cleared by a software sequence (an access to the SPICSR register followed by a write or a read to the SPIDR register). 0: Data transfer is in progress or the flag has been cleared 1: Data transfer between the device and an external device has been completed. <i>Note: While the SPIF bit is set, all writes to the SPIDR register are inhibited until the SPICSR register is read.</i>
6	WCOL	 Write Collision status This bit is set by hardware when a write to the SPIDR register is done during a transmit sequence. It is cleared by a software sequence (see <i>Figure 53</i>). 0: No write collision occurred 1: A write collision has been detected.
5	OVR	 SPI Overrun error This bit is set by hardware when the byte currently being received in the shift register is ready to be transferred into the SPIDR register while SPIF = 1 (see Overrun condition (OVR) on page 103). An interrupt is generated if SPIE = 1 in SPICR register. The OVR bit is cleared by software reading the SPICSR register. 0: No overrun error 1: Overrun error detected
4	MODF	 Mode Fault flag This bit is set by hardware when the SS pin is pulled low in master mode (see <i>Master mode fault (MODF) on page 103</i>). An SPI interrupt can be generated if SPIE = 1 in the SPICSR register. This bit is cleared by a software sequence (An access to the SPICR register while MODF = 1 followed by a write to the SPICR register). 0: No master mode fault detected 1: A fault in master mode has been detected.
3	-	Reserved, must be kept cleared.
2	SOD	 SPI Output Disable This bit is set and cleared by software. When set, it disables the alternate function of the SPI output (MOSI in master mode / MISO in slave mode). 0: SPI output enabled (if SPE = 1). 1: SPI output disabled.
1	SSM	 SS Management This bit is set and cleared by software. When set, it disables the alternate function of the SPI SS pin and uses the SSI bit value instead. See <i>Slave Select management on page 99</i>. 0: Hardware management (SS managed by external pin). 1: Software management (internal SS signal controlled by SSI bit. External SS pin free for general-purpose I/O).
0	SSI	 SS Internal mode This bit is set and cleared by software. It acts as a 'chip select' by controlling the level of the SS slave select signal when the SSM bit is set. 0: Slave selected. 1: Slave deselected.

Table 57. SPICSR register description



Transmitter

The transmitter can send data words of either 8 or 9 bits depending on the M bit status. When the M bit is set, word length is 9 bits and the 9th bit (the MSB) has to be stored in the T8 bit in the SCICR1 register.

Character transmission

During an SCI transmission, data shifts out LSB first on the TDO pin. In this mode, the SCIDR register consists of a buffer (TDR) between the internal bus and the transmit shift register (see *Figure 55*).

Procedure

- 1. Select the M bit to define the word length.
- 2. Select the desired baud rate using the SCIBRR and the SCIETPR registers.
- 3. Set the TE bit to assign the TDO pin to the alternate function and to send a idle frame as first transmission.
- 4. Access the SCISR register and write the data to send in the SCIDR register (this sequence clears the TDRE bit). Repeat this sequence for each data to be transmitted.

Clearing the TDRE bit is always performed by the following software sequence:

- 1. An access to the SCISR register
- 2. A write to the SCIDR register

The TDRE bit is set by hardware and it indicates:

- The TDR register is empty.
- The data transfer is beginning.
- The next data can be written in the SCIDR register without overwriting the previous data.

This flag generates an interrupt if the TIE bit is set and the I bit is cleared in the CCR register.

When a transmission is taking place, a write instruction to the SCIDR register stores the data in the TDR register and which is copied in the shift register at the end of the current transmission.

When no transmission is taking place, a write instruction to the SCIDR register places the data directly in the shift register, the data transmission starts, and the TDRE bit is immediately set.

When a frame transmission is complete (after the stop bit) the TC bit is set and an interrupt is generated if the TCIE is set and the I bit is cleared in the CCR register.

Clearing the TC bit is performed by the following software sequence:

- 1. An access to the SCISR register
- 2. A write to the SCIDR register

Note: The TDRE and TC bits are cleared by the same software sequence.



Bit	Name	Function
5	ADON	A/D Converter onThis bit is set and cleared by software.0: Disable ADC and stop conversion1: Enable ADC and start conversion
4	-	Reserved, must be kept cleared.
3:0	CH[3:0]	Channel selection These bits are set and cleared by software. They select the analog input to convert. 0000: Channel pin = AIN0 0001: Channel pin = AIN1 0010: Channel pin = AIN2 0011: Channel pin = AIN3 0100: Channel pin = AIN4 0101: Channel pin = AIN5 0110: Channel pin = AIN6 0111: Channel pin = AIN7 1000: Channel pin = AIN8 1001: Channel pin = AIN8 1001: Channel pin = AIN9 1010: Channel pin = AIN10 1011: Channel pin = AIN12 1101: Channel pin = AIN13 1110: Channel pin = AIN14 1111: Channel pin = AIN15 Note: The number of channels is device dependent. Refer to Section 2: Pin description.

Table 71. ADCCSR register description

ADC Data Register High (ADCDRH)



Table 72. ADCDRH register description

Bit	Name	Function
7:0	D[9:2]	MSB of Converted Analog Value



Mnemo	Description	Eunction/example	Det	Src	11	н	10	N	7	C
		I unction/example	DSI	510			10		2	<u> </u>
JRUGI	Jump if (C + Z = 0)	Unsigned >								
JRULE	Jump if $(C + Z = 1)$	Unsigned <=								
LD	Load	dst <= src	reg, M	M, reg				Ν	Z	
MUL	Multiply	X,A = X * A	A, X, Y	X, Y, A		0				0
NEG	Negate (2's compl)	neg \$10	reg, M					Ν	Z	С
NOP	No Operation									
OR	OR operation	A = A + M	А	М				Ν	Z	
POP	Pop from the Stack	pop reg	reg	М						
FUF		pop CC	CC	М	11	Н	10	Ν	Z	С
PUSH	Push onto the Stack	push Y	М	reg, CC						
RCF	Reset carry flag	C = 0								0
RIM	Enable Interrupts	11:0 = 10 (level 0)			1		0			
RLC	Rotate Left true C	C <= A <= C	reg, M					Ν	Z	С
RRC	Rotate Right true C	$C \Longrightarrow A \Longrightarrow C$	reg, M					Ν	Z	С
RSP	Reset Stack Pointer	S = Max allowed								
SBC	Subtract with Carry	A = A - M - C	А	М				Ν	Z	С
SCF	Set CARRY FLAG	C = 1								1
SIM	Disable Interrupts	11:0 = 11 (level 3)			1		1			
SLA	Shift Left Arithmetic	C <= A <= 0	reg, M					Ν	Z	С
SLL	Shift Left Logic	C <= A <= 0	reg, M					Ν	Z	С
SRL	Shift Right Logic	0 => A => C	reg, M					0	Z	С
SRA	Shift Right Arithmetic	A7 => A => C	reg, M					Ν	Z	С
SUB	Subtraction	A = A - M	А	М				Ν	Z	С
SWAP	SWAP nibbles	A7-A4 <=> A3-A0	reg, M					Ν	Z	
TNZ	Test for Neg and Zero	tnz lbl1						Ν	Z	
TRAP	S/W TRAP	S/W interrupt			1		1			
WFI	WAIT for Interrupt				1		0			
XOR	Exclusive OR	A = A XOR M	А	М				Ν	Z	

Table 82.	Instruction s	set overview ((continued)	





13.3 Thermal characteristics

Table 115. Thermal characterist	CS
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Symbol	Ratings	Value	Unit
R _{thJA}	Package thermal resistance (junction to ambient): LQFP44 10x10 LQFP327x7	52 70	°C/W
PD	Power dissipation ⁽¹⁾	500	mW
T _{Jmax}	Maximum junction temperature ⁽²⁾	150	°C

1. The maximum power dissipation is obtained from the formula $P_D = (T_J - T_A) / R_{thJA}$. The power dissipation of an application can be defined by the user with the formula: $P_D = P_{INT} + P_{PORT}$ where P_{INT} is the chip internal power ($I_{DD} \times V_{DD}$) and P_{PORT} is the port power dissipation depending on the ports used in the application.

2. The maximum chip-junction temperature is based on technology characteristics.

13.4 Ecopack information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

13.5 Packaging for automatic handling

The devices can be supplied in trays or with tape and reel conditioning.

Tape and reel conditioning can be ordered with pin 1 left-oriented or right-oriented when facing the tape sprocket holes as shown in *Figure 89*.

Figure 89. pin 1 orientation in tape and reel conditioning



See also Figure 90: ST72F324Bxx-Auto Flash commercial product structure on page 182 and Figure 91: ST72P324Bxx-Auto FastROM commercial product structure on page 184.



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